



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	DZWB*D6BALZB	A	ZS1A	2016-11-11
Amount	UoM	Unit type	ST ECOPACK Grade	
16.78	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	2.9x1.625x1.175	6	gull wing	
Comment	Package: WB SOT 23 - 6L; MDF valid for STM6710LWB6F			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	DZWB*D6BALZB					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.928	mg	supplier	die	Silicon (Si)	7440-21-3		0.903	mg	973060	53814
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	5388	298
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	2155	119
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1078	60
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.003	mg	3233	179
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.014	mg	15086	834
Leadframe	Other inorganic materials	7.960	mg	supplier	alloy	Copper (Cu)	7440-50-8		7.704	mg	967839	459118
				supplier	alloy	Iron (Fe)	7439-89-6		0.195	mg	24497	11621
				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	251	119
				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1131	536
				supplier	metallization	Nickel (Ni)	7440-02-0		0.046	mg	5779	2741
				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	377	179
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	126	60
				supplier	metallization							
Die Attach	Other Organic Materials	0.078	mg	supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.022	mg	282051	1311
				supplier	glue	Aromatic amine	Proprietary		0.003	mg	38462	179
				supplier	glue	Glycol ether ester	Proprietary		0.003	mg	38462	179
				supplier	glue	silica	60676-86-0		0.024	mg	307692	1430
				supplier	glue	Aluminium oxide	1344-28-1		0.026	mg	333333	1549
Bonding wire	Precious metals	0.139	mg	supplier	wire	Gold (Au)	7440-57-5		0.139	mg	1000000	8284
encapsulation	Other Organic Materials	7.675	mg	supplier	mold compound	Silica, vitreous	60676-86-0		6.705	mg	873616	399583
				supplier	mold compound	phenolic resin	Proprietary		0.375	mg	48860	22348
				supplier	mold compound	epoxy resin	Proprietary		0.364	mg	47427	21692
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.208	mg	27101	12396
				supplier	mold compound	carbon black	1333-86-4		0.016	mg	2085	954